Plastic Packages for Integrated Circuits

Package Outline Drawing
L8.3x3G
8 LEAD THIN DUAL FLAT NO-LEAD PLASTIC PACKAGE (TDFN)
Rev 1, 5/15

NOTES:
1. Controlling dimensions are in mm.
   Dimensions in ( ) for reference only.
2. Unless otherwise specified, tolerance: Decimal ±0.05
   Angular ±2°
3. Dimensioning and tolerancing conform to JEDEC STD MO220-D.
4. The configuration of the pin #1 identifier is optional, but must be
   located within the zone indicated. The pin #1 identifier may be either
   a mold or mark feature.
5. Tiebar shown (if present) is a non-functional feature and may be
   located on any of the 4 sides (or ends).